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EUROPEAN PATENT OFFICE

Patent Abstracts of Japan

PUBLICATION NUMBER : 06029632
PUBLICATION DATE : 04-02-94

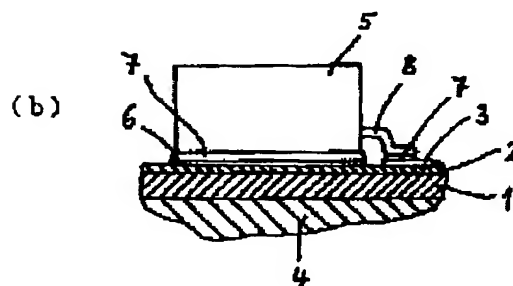
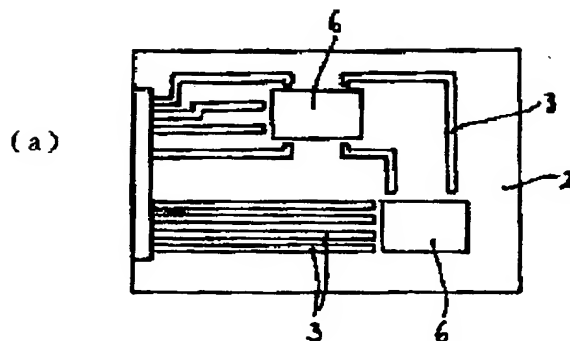
APPLICATION DATE : 15-02-93
APPLICATION NUMBER : 05025563

APPLICANT : RHEINMETALL GMBH;

INVENTOR : SOMMER PETER;

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TITLE : PRINTED CIRCUIT BOARD



ABSTRACT : PURPOSE: To provide an improved printed circuit board, wherein a means for removing heat from a high electric power semiconductor is improved.

CONSTITUTION: A printed circuit board comprises a steel hybrid substrate 1 comprising first and second surfaces, while the second surface is connectable to a heat sink 4. A pattern of electric conductor 3 and a metallic island 6 electrically insulated from it are printed on the first surface. The metallic island 6 can be connected to a high electric power semiconductor 5.

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